



Material Content Data Sheet



Sales Product Name		BAS 16W H6327		Issued		2. August 2018		
MA#		MA000845538						
Package		PG-SOT323-3-1		Weight*		5.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		3	
	noble metal	gold	7440-57-5	0.002	0.03		339	
	inorganic material	silicon	7440-21-3	0.017	0.29	0.32	2900	3242
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		442	
	non noble metal	chromium	7440-47-3	0.008	0.13		1325	
	non noble metal	copper	7440-50-8	2.617	43.98	44.16	439797	441652
wire	non noble metal	copper	7440-50-8	0.003	0.05	0.05	460	460
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5307	
	plastics	epoxy resin	-	0.679	11.41		114092	
	inorganic material	silicondioxide	60676-86-0	2.447	41.13	53.07	411263	530662
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22301	22301
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1683	1683
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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